

20V N-Channel MOSFET

General Description

- Trench Power LV MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low RDS(ON)

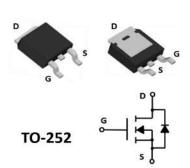
Applications

- High current load applications
- Load switching
- Hard switched and high frequency circuits
- Uninterruptible power supply

Product	Summary
TTOULOU	Ourinnary



BVDSS	20	V
RDS(on),Typ.@VGS=4.5V	4.5	mΩ
ID	60	А



Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Parameter		Symbol	Limit	Unit	
Drain-source Voltage		V _{DS}	20	V	
Gate-source Voltage		V _{GS}	±10	V	
Drain Current	T _c =25℃		60	A	
Drain Current	T _C =100℃	- I _D	42	A	
Pulsed Drain Current ^A		I _{DM}	210	А	
Total Dower Dissipation	T _c =25°C	P	35	W	
Total Power Dissipation	T _C =100℃	PD	18	W	
Single Pulse Avalanche Energy ^B		E _{AS}	195	mJ	
Thermal Resistance Junction-to-Case ^c		$R_{ extsf{ heta}JC}$	4.3	°C/W	
Junction and Storage Temperature Range		T _J ,T _{STG}	-55~+175	°C	



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Electrical Characteristics (T = 25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Тур	Мах	Units
Static Parameter			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V_{GS} = 0V, I _D =250µA	20			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V,V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{GSS}	V_{GS} = ±10V, V_{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V_{DS} = V_{GS} , I_D =250 μ A	0.4	0.62	1.0	V
		V _{GS} = 4.5V, I _D =20A		4.5	6.0	mΩ
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} = 2.5V, I _D =15A		5.5	8.8	
		V _{GS} = 1.8V, I _D =10A		8.0	14	
Diode Forward Voltage	V _{SD}	I _S =20A,V _{GS} =0V			1.2	V
Maximum Body-Diode Continuous Current	Is				60	А
Dynamic Parameters						
Input Capacitance	C _{iss}			2450		pF
Output Capacitance	C _{oss}	V_{DS} =10V, V_{GS} =0V,f=1MHZ		430		
Reverse Transfer Capacitance	C _{rss}			205		
Switching Parameters						
Total Gate Charge	Qg	V _{GS} =4.5V,V _{DS} =10V,I _D =15A		65		
Gate-Source Charge	Q _{gs}			15		0
Gate-Drain Charge	Q _{gd}			13		nC
Reverse Recovery Charge	Qrr			39		
Reverse Recovery Time	t _{rr}	I _F =15A, di/dt=100A/us		35		
Turn-on Delay Time	t _{D(on)}	V_{GS} =4.5V, V_{DD} =10V, I_D =10A, R_L =1 Ω		12		
Turn-on Rise Time	tr			26		ns
Turn-off Delay Time	t _{D(off)}	$R_{GEN}=3\Omega$		35		
Turn-off fall Time	t _f			10		

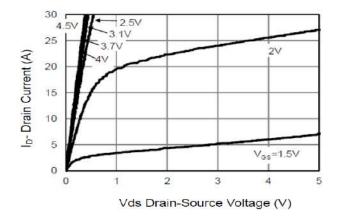
A. Pulse Test: Pulse Width ${\leqslant}300 us, Duty \ cycle {\leqslant}2\%.$

B. $T_j=25^{\circ}C$, $V_{DD}=15V$, $V_G=10V$, L=0.5mH, $R_g=25^{\circ}\Omega$

C. R_{BJA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{BJC} is guaranteed by design, while R_{BJA} is determined by the board design. The maximum rating presented here is based on mounting on a 1 in 2 pad of 2oz copper.



Typical Performance Characteristics





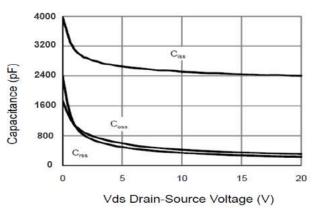


Figure3. Capacitance Characteristics

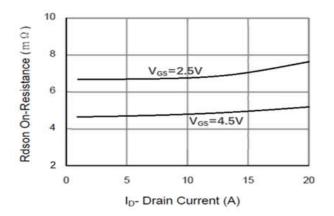


Figure 5. Drain-Source on Resistance

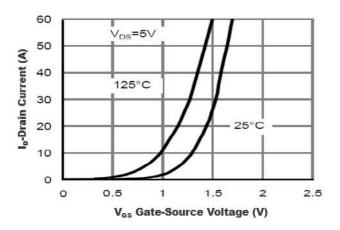
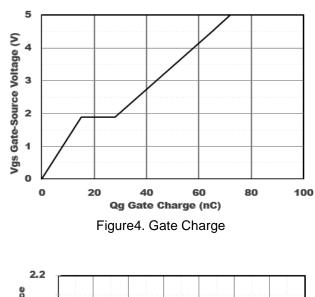


Figure2. Transfer Characteristics



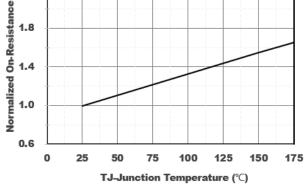


Figure6. Drain-Source on Resistance



ASDM20N60AKQ 20V N-Channel MOSFET

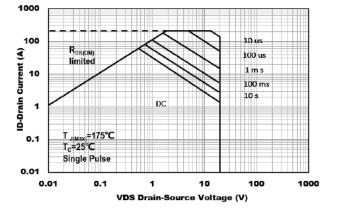


Figure7. Safe Operation Area

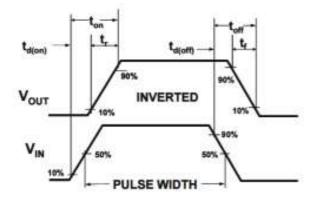


Figure8. Switching wave



Ordering and Marking Information

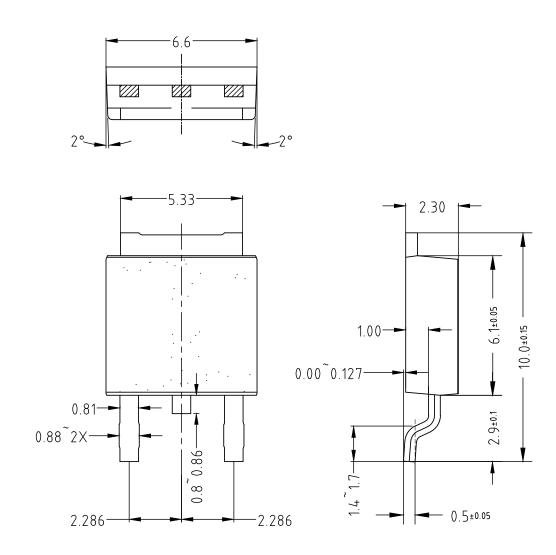
Ordering Device No.	Marking	Package	Packing	Quantity
ASDM20N60AKQ-R	20N60A	TO-252	Tape&Reel	2500/Reel

PACKAGE	MARKING
TO-252	AS □□□ 20N6OA □□□□ → Date Code

ASDM20N60AKQ

20V N-Channel MOSFET

TO-252





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